Product / Package Information

Package	SC70
Body Size	
Lead Count	3
Terminal Finish	NiPdAu

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	3.78 E-03	87.30	873000	53.30	532955
Thermosets	Phenol Resin	Proprietary	1.95 E-04	4.50	45000	2.75	27472
Thermosets	Epoxy Resin 1	Proprietary	1.30 E-04	3.00	30000	1.83	18315
Thermosets	Epoxy Resin 2	Proprietary	1.30 E-04	3.00	30000	1.83	18315
Others	Others	Proprietary	8.67 E-05	2.00	20000	1.22	12210
Other inorganic materials	Carbon Black	1333-86-4	8.67 E-06	0.20	2000	0.12	1221
Subtotal			4.33 E-03	100.0	1000000	61.05	610487

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.33 E-03	97.5	975000	32.81	328100
Copper & its alloys	Iron	7439-89-6	5.61 E-05	2.35	23500	0.79	7908
Copper & its alloys	Zinc	7440-66-6	2.87 E-06	0.12	1200	0.04	404
Copper & its alloys	Phosphorus	7723-14-0	7.17 E-07	0.03	300	0.01	101
Subtotal			2.39 E-03	100	1000000	33.65	336513

Internal/External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.78 E-05	90.91	909091	0.39	3919
Precious metals	Palladium	7440-05-3	2.42 E-06	7.91	79051	0.03	341
Precious metals	Gold	7440-57-5	3.63 E-07	1.19	11858	0.01	51
Subtotal			3.06 E-05	100.00	1000000	0.43	4311

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.99 E-05	99.99	1000000	0.56	5617

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.79 E-04	100	1000000	3.93	39326

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Aluminum oxide	1344-28-1	9.31 E-06	35	350000	0.13	1311
Other organic materials	Diethylene glycol monoethyl ether acetate	112-15-2	9.31 E-06	35	350000	0.13	1311
Thermoset	Epoxy Resin	TS ref#10114	6.65 E-06	25	250000	0.09	936
Others	Amine	TS ref#10039	1.33 E-06	5	50000	0.02	187
Subtotal			2.66 E-05	100	1000000	0.37	3745

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.10 E-03**	**100**	**1000000**

Control ID: MS010757BPKG890
Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

AHEAD OF WHAT'S POSSIBLE™

ADI Proprietary